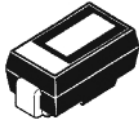
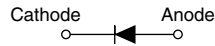


Schottky Rectifier, 2 A


SMB


FEATURES

- Small foot print, surface mountable
- Very low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Lead (Pb)-free ("PbF" suffix)
- Designed and qualified for industrial level


RoHS*
COMPLIANT

PRODUCT SUMMARY

$I_{F(AV)}$	2.0 A
V_R	30 V

DESCRIPTION

The 20BQ030PbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and small foot prints on PC boards. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
$I_{F(AV)}$	Rectangular waveform	2.0	A
V_{RRM}		30	V
I_{FSM}	$t_p = 5 \mu s$ sine	350	A
V_F	2.0 Apk, $T_J = 125^\circ C$	0.37	V
T_J	Range	- 55 to 150	$^\circ C$

VOLTAGE RATINGS

PARAMETER	SYMBOL	20BQ030PbF	UNITS
Maximum DC reverse voltage	V_R	30	V
Maximum working peak reverse voltage	V_{RWM}		

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	50 % duty cycle at $T_L = 119^\circ C$, rectangular waveform	2.0	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	5 μs sine or 3 μs rect. pulse	350	
		10 ms sine or 6 ms rect. pulse	80	
Non-repetitive avalanche energy	E_{AS}	$T_J = 25^\circ C$, $I_{AS} = 1 A$, $L = 6 mH$	3.0	mJ
Repetitive avalanche current	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical	1.0	A

* Pb containing terminations are not RoHS compliant, exemptions may apply

ELECTRICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop	$V_{FM}^{(1)}$	2 A	$T_J = 25\text{ }^\circ\text{C}$	0.470	V
		4 A		0.550	
		2 A	$T_J = 125\text{ }^\circ\text{C}$	0.370	
		4 A		0.470	
Maximum reverse leakage current	$I_{RM}^{(1)}$	$T_J = 25\text{ }^\circ\text{C}$	$V_R = \text{Rated } V_R$	0.5	mA
		$T_J = 125\text{ }^\circ\text{C}$		15	
Maximum junction capacitance	C_T	$V_R = 5 V_{DC}$, (test signal range 100 kHz to 1 MHz) $25\text{ }^\circ\text{C}$		200	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		2.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R		10 000	V/ μ s

Note

(1) Pulse width < 300 μ s, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum junction and storage temperature range	$T_J^{(1)}$, T_{Stg}			- 55 to 150	$^\circ\text{C}$
Maximum thermal resistance, junction to lead	$R_{thJL}^{(2)}$	DC operation		25	$^\circ\text{C/W}$
Maximum thermal resistance, junction to ambient	R_{thJA}			80	
Approximate weight				0.10	g
				0.003	oz.
Marking device		Case style SMB (similar DO-214AA)		V2E	

Notes

(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

(2) Mounted 1" square PCB

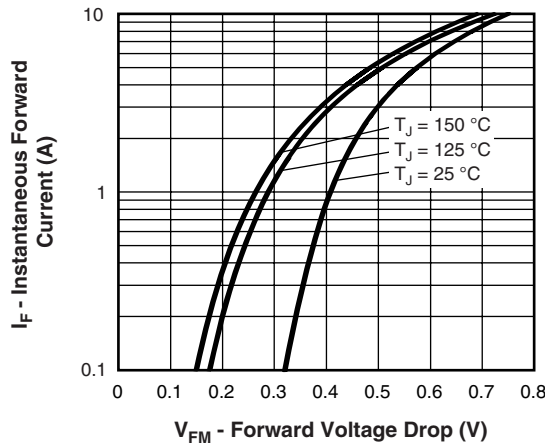


Fig. 1 - Maximum Forward Voltage Drop Characteristics

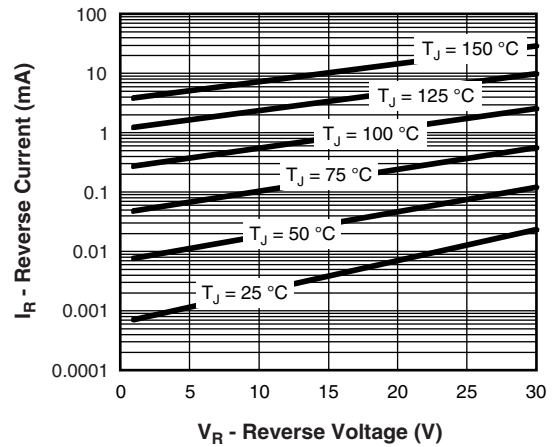


Fig. 2 - Typical Peak Reverse Current vs. Reverse Voltage

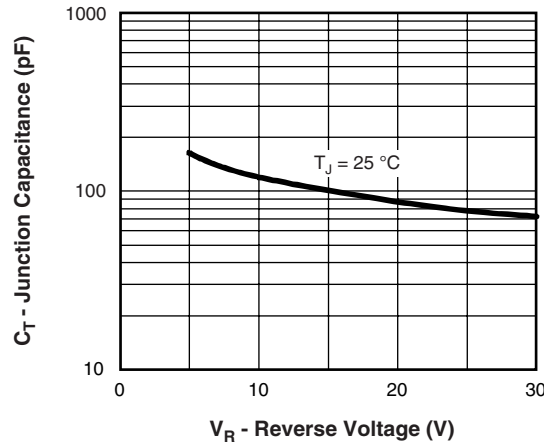
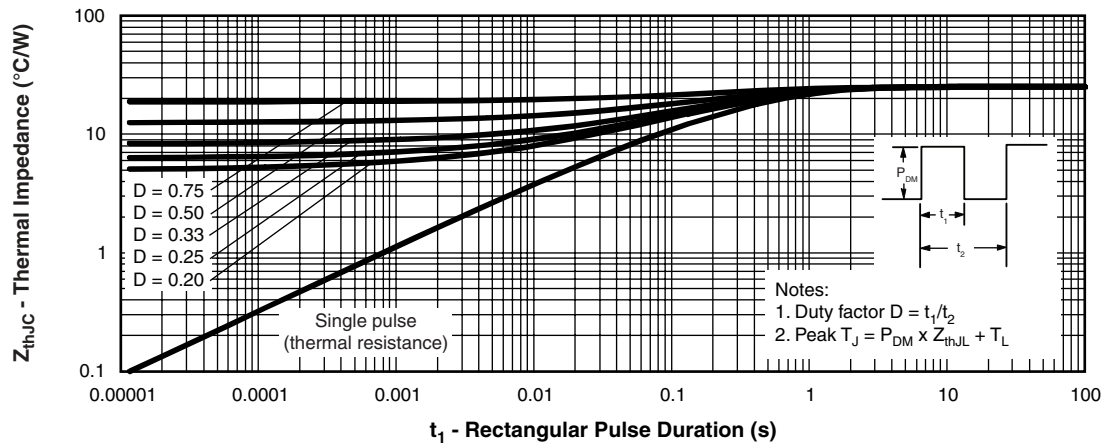


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage


 Fig. 4 - Maximum Thermal Impedance Z_{thJL} Characteristics

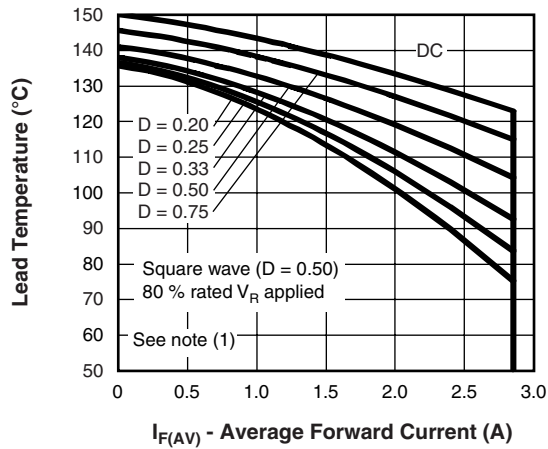


Fig. 5 - Maximum Average Forward Current vs. Allowable Lead Temperature

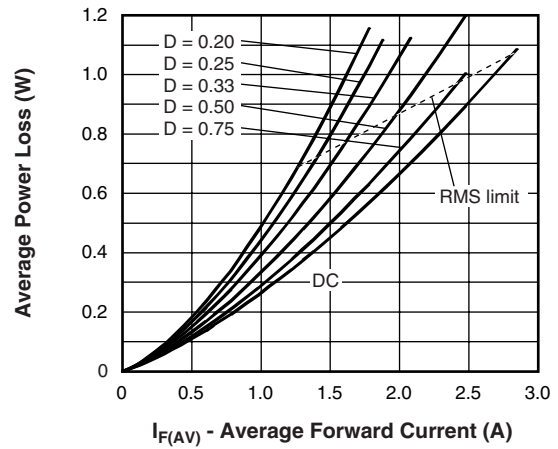


Fig. 6 - Maximum Average Forward Dissipation vs. Average Forward Current

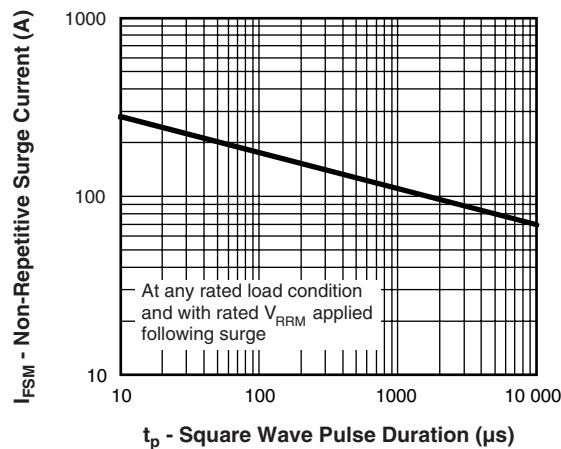


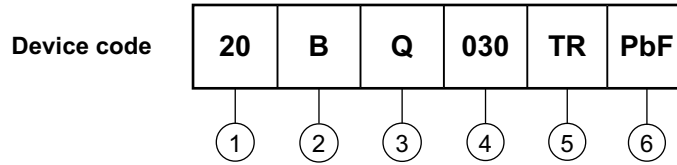
Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

Note

- (1) Formula used: $T_L = T_J - (Pd + Pd_{REV}) \times R_{thJL}$;
 Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 Pd_{REV} = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = 80% rated V_R



ORDERING INFORMATION TABLE



- 1** - Current rating
- 2** - B = Single lead diode
- 3** - Q = Schottky "Q" series
- 4** - Voltage rating (030 = 30 V)
- 5** -
 - None = Box (1000 pieces)
 - TR = Tape and reel (3000 pieces)
- 6** -
 - None = Standard production
 - PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95017
Part marking information	http://www.vishay.com/doc?95029
Packaging information	http://www.vishay.com/doc?95034
SPICE model	http://www.vishay.com/doc?95284



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